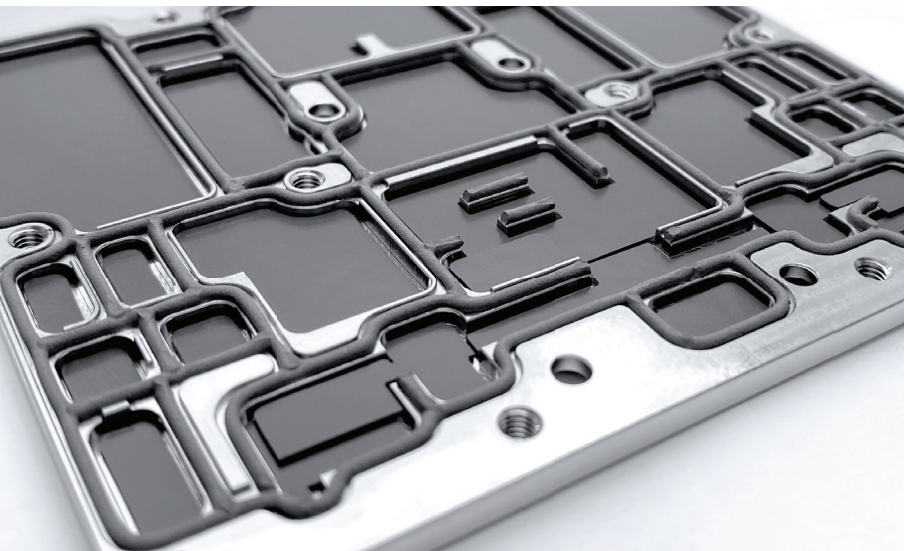


EMI Shielding Material

Conductive Form-In-Place Gasket



MATERIAL

Soft conductive silicon that requires a lower compression force.

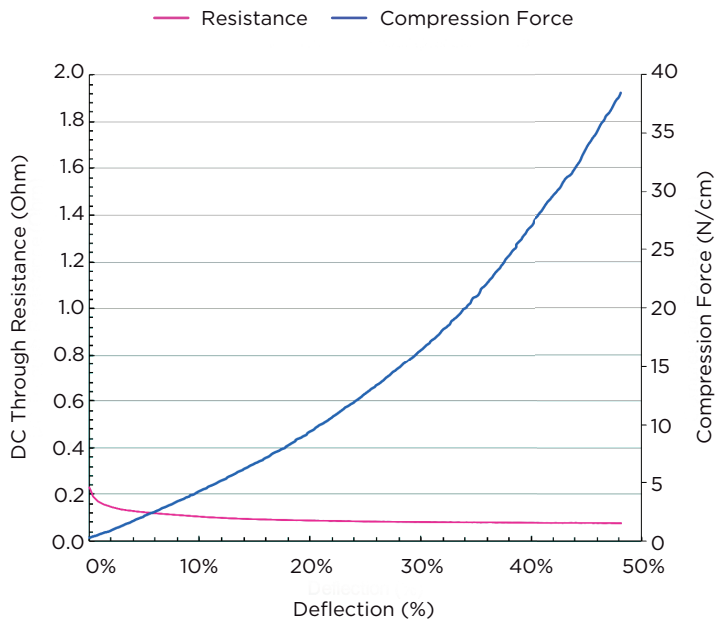


FEATURES

- Enhanced resistance to galvanic corrosion and stability in severe environments
- Extremely soft and small gasket profiles

Force-Deflection-Resistance of F5304 Gasket

D Shape 1.0 mm(H) * 1.3 mm(W)
Rate of Strain, 1.5mm/min



PROPERTIES	F5304
Elastomer Binder	Silicone
Conductive Filler	Ni/Gr
Cure System	Thermal
Density	2.0 g/cm ³
Hardness	30 Shore A
Adhesion on Al Metal	>80 N/cm ²
Tensile Strength	120 psi
Tear Strength	30 Lbf/in
Operating Temperature	-45 to 150 °C
Flammability Rating (UL94V-0)	E303387
DC-Through Resistance @ 30% Compression, 1mm H	0.08 Ohm
Shielding Effectiveness 200 MHz - 40 GHz	>100 dB
Min. Bead Height	0.3 mm

GET IN TOUCH

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